DATA SHEET

Part No.	AN13300A		
Package Code No.	*SOP022 - P - 0375C		

SEMICONDUCTOR COMPANY MATSUSHITA ELECTRIC INDUSTRIAL CO., LTD.

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AN13300A Silicon Monolithic Bipolar IC

Features

• Video signal input - output interface for DSP

Applications

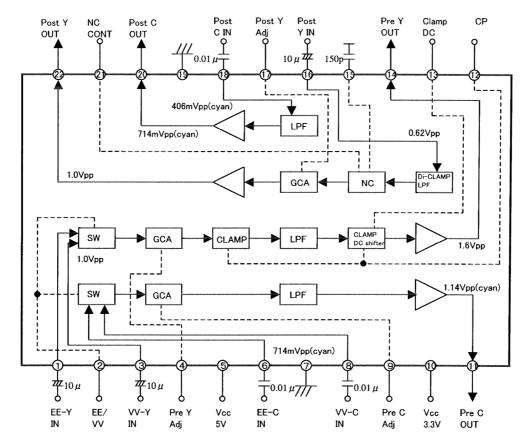
• VCR (Digital Video equipment)

Package

• Dill - 22Pin plastic package SO Type

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Block Diagram



■Pin Descriptions

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Pin No.	Function	Impedance	Pin No.	Function	Impedance
1	EE - Y IN	30k	12	Clamp Pulse IN	210k
2	EE / VV SW	210k	13	Clamp DC	65k
3	VV - Y IN	30k	14	Pre - Y OUT	E. F.
4	Pre - Y Adj.	64k	15	N. C. Capacitor	500k
5	V _{CC1} (5V)		16	Post - Y IN	26k
6	EE - C IN	30k	17	Post - Y Adj.	65k
7	GND		18	Post - C IN	21k
8	VV - C IN	10k	19	GND	
9	Pre - C Adj.	62k	20	Post - C OUT	E. F.
10	V _{CC2} (3.3 V)		21	N. C. Control	65k
11	Pre - C OUT	E. F.	22	Post - Y OUT	E. F.

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■ Absolute Maximum Ratings

No.	Parameter	Symbol	Rating		Unit	Note
1	Storage temperature	T _{stg}	-55 to +125		°C	*
2	Operating ambient temperature	T _{opr}	-20 to +70		°C	*
3	Operating ambient atmospheric pressure	P _{opr}	$1.013 \times 10^5 \pm 0.61 \times 10^5$		Pa	
4	Operating constant gravity	G _{opr}	9 810		m/S ²	
5	Operating shock	S _{opr}	4 900		m/S ²	
6	6 Supply voltage	V _{CC}	V _{CC1}	5.5	v	
0			V _{CC2}	3.6		
7	7 Supply current	т	I _{CC1}	35		
		I _{CC}	I _{CC2}	0.5	mA	
8	Power dissipation	P _D	195		W	

Note) *:	Expect for the op	erating ambient	temperature and	storage temperature	, all ratings are for	Ta = 25° C.

Operating Supply Voltage Range

	V _{CC1}	4.75 V to 5.25 V
Operating supply voltage range	V _{CC2}	3.1 V to 3.5 V

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